

REMARKS

Applicant has amended the title as requested in the Office Action and provided a new Abstract.

Applicant has also rewritten Claims 31 and 32 as new Claims 37 and 38 so as to address the rejections under 35 U.S.C. §112, second paragraph, and to clarify the present invention.

As now claimed, Applicant's invention is to a method of forming a plurality of wiring lines of conductive material on a board to form a printed circuit board. The method involves forming a plurality of wiring lines, having first and second portions, and a uniform thickness on the board, and then etching a first of the plurality of wiring lines, such that the height of the first portion is thinner than that of the second portion. Such a method is not taught or suggested in the reference cited.

In the Office Action, Applicant's claims were rejected as being anticipated under 35 U.S.C. §102(b) in view of Takahashi et al. (U.S. 4,413,309). Reconsideration and removal of this rejection is respectfully requested in view of the present rewriting of the claims and the following remarks.

In the Office Action, it is alleged that the Takahashi et al. reference shows, in Figure 1, a plurality of wiring lines with different thicknesses formed by chemical etching in different portions thereof.

The Takahashi et al. reference, however, upon careful review, shows conductive patterns (4) which have pilot patterns (7) of a different thickness, in the width direction, than the lead (2) for leadless elements and leads (3) for elements with leads.

In the present claimed method, however, and as described in the present specification, the wiring lines are etched so as to have first and second portions, with a first portion being thinner, in a height direction than the second portion. This is clearly shown in the drawings and described in the present specification. With this method, a high-density printed circuit board is produced which has reduced crosstalk noise. This is completely distinct from the teachings of Takahashi, et al.

Claims 37 and 38, as now presented clearly provide that the method is one wherein etching of a first of a plurality of wiring lines is effected such that a first portion thereof is thinner, in height, than a second portion thereof.

In view of the present clarification of the claims and above remarks, Applicant's Claims 37 and 38 are believed to be patentable over the prior art and early action towards allowance thereof is respectfully requested.


If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

U.S. Patent Application Serial No. 09/928,441

In the event that this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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Enclosure: Substitute Abstract of the Disclosure